



Spec No. : Effective Date: Revision:



1. Description

The LiteON 5630 Product series is a wide beam angle standard-dimension package, combining the lifetime and reliability advantages of Light Emitting Diodes with the brightness of conventional lighting. It gives you total design freedom and unmatched brightness, creating a new opportunities for solid state lighting to displace conventional lighting technologies.

1.1 Features

- Package in 8mm tape on 7" diameter reels.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- EIA STD package.
- I.C. compatible.
- Meet green product and Pb-free(According to RoHS)

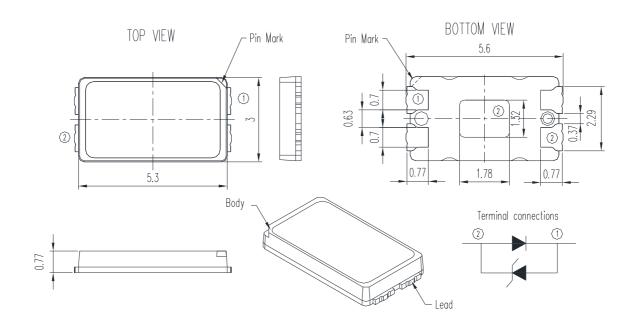
1.2 Available Part Numbers

ССТ	Part Number
6500K	LTW-5630AQL65
5700K	LTW-5630AQL57
5000K	LTW-5630AQL50
4000K	LTW-5630AQL40
3500K	LTW-5630AQL35
3000K	LTW-5630AQL30
2700K	LTW-5630AQL27

Part No. : LTW-5630AQLxx Series BNS-OD-FC002/A4



2. Outline Dimensions



Part No.	Lens Color	Source Color
LTW-5630AQL65		
LTW-5630AQL57		
LTW-5630AQL50		
LTW-5630AQL40	Orange	InGaN Blue
LTW-5630AQL35		
LTW-5630AQL30		
LTW-5630AQL27		

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ± 0.2 mm (.008") unless otherwise noted.



3. Absolute Maximum Ratings at T_a=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	Po	656	mW
Continuous Forward Current	I _F	200	mA
Pulse Forward Current	I _{FP}	260	mA
Operating Temperature Range	T _{opr}	-40 ~ +85	°C
Storage Temperature Range	T _{stg}	-40 ~ +100	°C
Junction Temperature	T _j	≦120	°C

Notes:

- 1. 1/10 duty cycle, Pulse width \leq 100 μ s.
- 2. Forbid to operating at reverse voltage condition for long.
- 3. It is recommended to follow de-rating curve to use maximum rating to ensure LED can operated normally.



4. Electro-Optical Characteristics

4.1 Typical Performance

Parameter	Symbol				Unit	Test Condition					
Correlated Color Temp.	ССТ	Тур.	2700	3000	3500	4000	5000	5700	6500	'K	
Chromaticity	Х	Тур.	0.458	0.434	0.408	0.382	0.345	0.329	0.312		
Coordinates	у	Тур.	0.410	0.403	0.392	0.380	0.355	0.342	0.328	-	
		Min	33.5	35.0	36.5	36.5	36.5	36.5	36.5		
Luminous Flux ¹	Фи	Тур.	42.0	44.5	45.3	45.3	45.3	46.2	44.5	lm	
		Max.	51.5	53.0	54.5	54.5	54.5	54.5	54.5		
Optical Efficiency	η_{opt}	Тур.	117	124	126	126	126	128	124	lm/W	/ 400m A
Color Rendering Index	CRI	Min.				90		-	<i>I</i> _F = 120mA		
Viewing Angle	2θ _{1/2}	Тур.				120				deg	
		Min				2.8					
Forward Voltage	V_{F}	Тур.				3.0				V	
	Max. 3.3										
Thermal Resistance	R _{jt}	Тур.	o. 15							°C/W	
ESD-Withstand Voltage	ESD	Min	n 5K								V

Notes

- 1. Luminous flux is the total luminous flux output as measured with an integrating sphere.
- 2. Iv (flux Φ_v) classification code is marked on each packing bag.
- 3. The chromaticity coordinates (x, y) is derived from the 1931 CIE chromaticity diagram.
- 4. Caution in ESD:

Static Electricity and surge damages the LED. It is recommended using a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

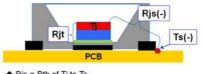
- 5. CAS140B is the test standard for the chromaticity coordinates (x, y) & $\Phi_{\rm v}$.
- 6. The chromaticity coordinates (x, y) guarantee should be added +/- 0.01 tolerances
- 7. CRI measurement allowance is ±5, R9 is >50.
- 8. The thermal resistance is defined

as the figure, Rit is the Rth from Ti to thermal pad solder:

Reference for thermal resistance:

Using 2.5x 2.5x 0.17 cm aluminum MCPCB,

 R_{it} =15°C/W, R_{is} =19°C/W

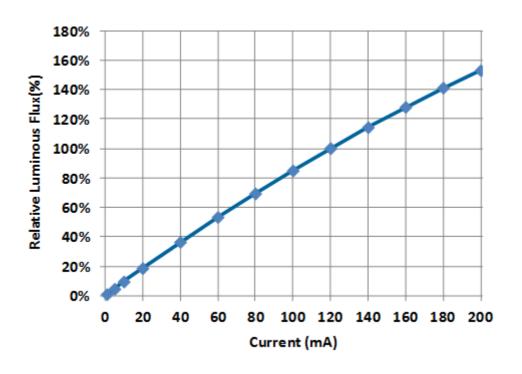


- Rjs = Rth of Tj to Ts
- ◆ Rjt = Rth of Tj to Thermal pad solder
 ◆ Rth definition in Datasheet = Rjt
- ◆ Rjt < Rjc ◆ Tj = Rjs*W+Ts



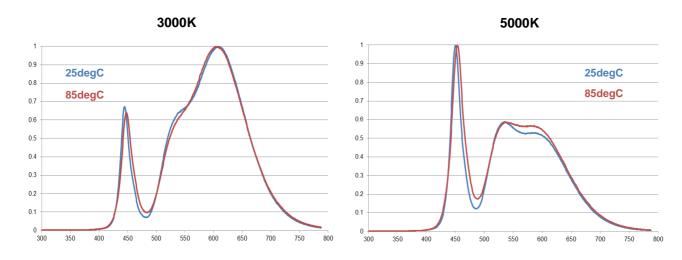
4.2 Forward Current vs. Lumen and Voltage

Current	VF				Lume	n (lm)		
(mA)	(V)	2700K	3000K	3500K	4000K	5000K	5700K	6500K
20	2.72	7.5	8.0	8.1	8.1	8.1	8.2	8.0
40	2.80	14.7	15.7	16.0	16.0	16.0	16.3	15.7
60	2.86	21.6	23.0	23.4	23.4	23.4	23.7	22.9
80	2.92	28.0	30.0	30.5	30.4	30.4	31.0	30.0
100	2.98	34.5	36.7	37.3	37.3	37.3	38.0	36.6
120	3.03	42.0	44.5	45.3	45.3	45.3	46.2	44.5
140	3.08	46.3	49.2	50.1	50.2	50.2	51.1	49.3
160	3.14	52.0	55.3	56.3	56.3	56.3	57.2	55.3
180	3.18	57.2	60.9	62.0	62.0	62.0	63.1	60.9
200	3.23	62.0	66.0	67.2	67.2	67.2	68.3	66.0

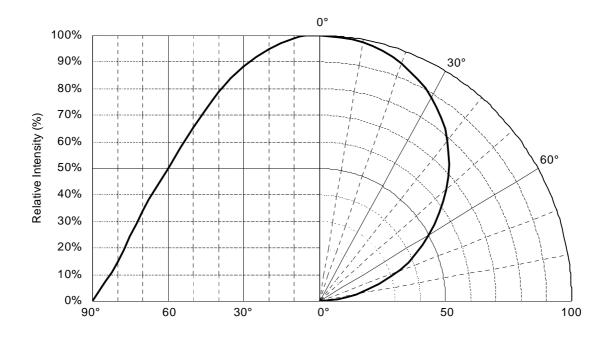




4.3 Relative Spectral Power Distribution at Typical Current

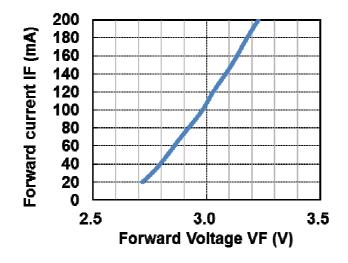


4.4 Radiation Characteristics

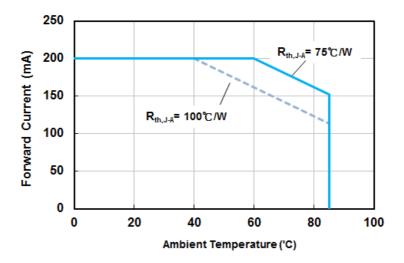




4.5 Forward Current vs. Forward Voltage

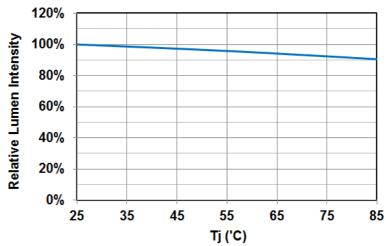


4.6 Forward Current Derating Curve vs. Ambient Temperature

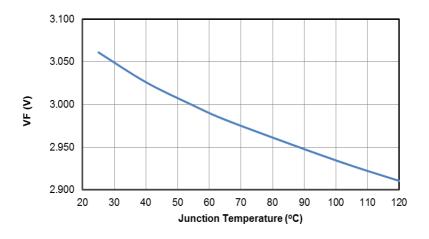




4.7 Relative Intensity vs. Junction Temperature



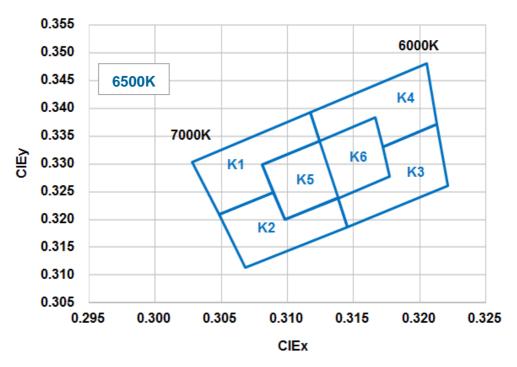
4.8 Forward Voltage vs. Junction Temperature

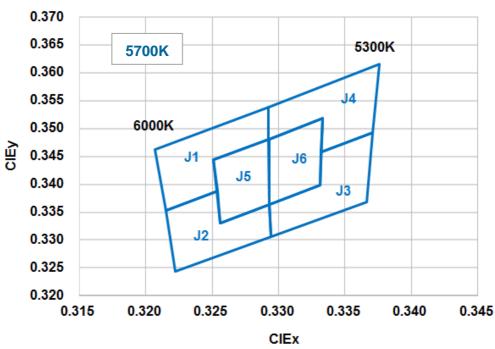




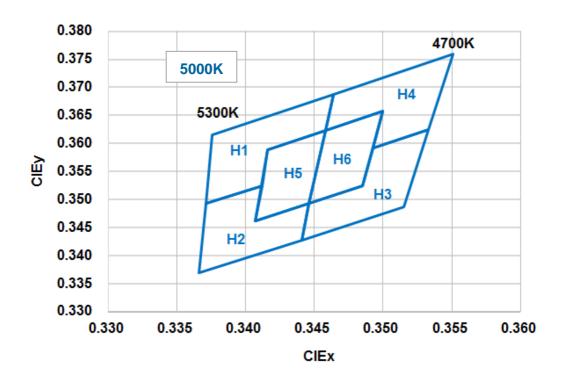
5. Binning Definition

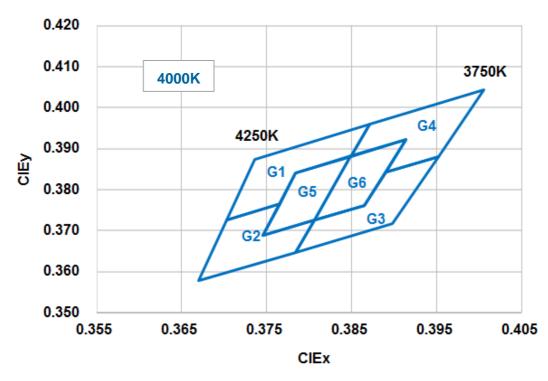
5.1 Color Bin



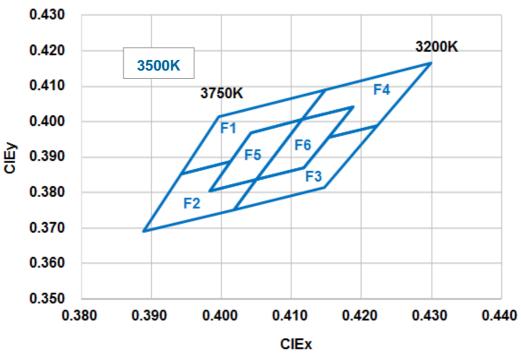


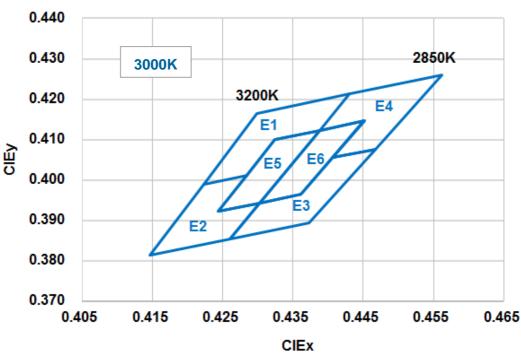




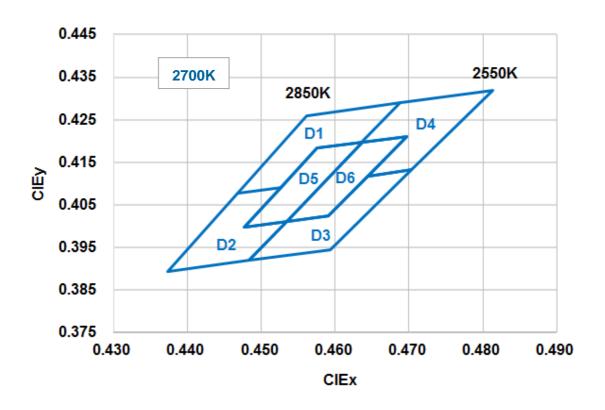














5.2 Color Rank

				65	500K	(<i>I</i> _F = 120	mA)				
Rank	-	х	у	Rank	-	x	у	Rank	-	х	у
	1	0.3048	0.3209		1	0.3145	0.3187		1	0.3098	0.320
	2	0.3028	0.3304		2	0.3138	0.3238		2	0.3081	0.3299
K1	3	0.3117	0.3393	К3	3	0.3177	0.3277	K5	3	0.3124	0.3342
N.I	4	0.3124	0.3341		4	0.3172	0.3330		4	0.3138	0.3239
	5	0.3081	0.3299		5	0.3213	0.3371				
	6	0.3089	0.3249		6	0.3221	0.3261				
	1	0.3068	0.3113		1	0.3117	0.3393		1	0.3138	0.3239
	2	0.3048	0.3209		2	0.3205	0.3481		2	0.3124	0.3342
K2	3	0.3089	0.3249	V 4	3	0.3213	0.3371	K6	3	0.3167	0.3384
NZ	4	0.3098	0.32	K4	4	0.3172	0.333	Νō	4	0.3178	0.3277
	5	0.3138	0.3238		5	0.3166	0.3384				
	6	0.3145	0.3187		6	0.3124	0.3341				

Tolerance on each Hue bin (x,y) is \pm -0.01.

				57	700K	$(I_{\rm F}=120$	mA)				
Rank	-	x	у	Rank	-	x	у	Rank	-	x	У
	1	0.3215	0.3353		1	0.3294	0.3306		1	0.3256	0.3331
	2	0.3207	0.3462		2	0.3293	0.3364		2	0.3251	0.3444
J1	3	0.3292	0.3539	J3	3	0.3331	0.3398	J5	3	0.3292	0.3481
31	4	0.3292	0.3481		4	0.3332	0.3458		4	0.3293	0.3364
	5	0.3251	0.3444		5	0.3371	0.3493				
	6	0.3254	0.3388		6	0.3366	0.3369				
	1	0.3222	0.3243		1	0.3292	0.3539		1	0.3293	0.3364
	2	0.3215	0.3353		2	0.3376	0.3616		2	0.3293	0.3481
J2	3	0.3254	0.3388	14	3	0.3371	0.3493	ıe	3	0.3333	0.3518
JZ	4	0.3256	0.3331	J4 -	4	0.3332	0.3458	J6	4	0.3331	0.3398
	5	0.3293	0.3364		5	0.3333	0.3518	-			
	6	0.3294	0.3306		6	0.3292	0.3481				



				50	000K	(<i>I</i> _F = 120	mA)				
Rank	-	х	у	Rank	-	х	у	Rank	-	х	у
	1	0.3371	0.3493		1	0.3441	0.3428		1	0.3407	0.3462
	2	0.3376	0.3616		2	0.3446	0.3493		2	0.3416	0.3589
114	3	0.3464	0.3688	Н3	3	0.3485	0.3524	ue.	3	0.3458	0.3623
H1	4	0.3458	0.3623	пэ	4	0.3493	0.3591	H5	4	0.3446	0.3493
	5	0.3416	0.3589		5	0.3533	0.3624				
	6	0.3412	0.3525		6	0.3515	0.3487				
	1	0.3366	0.3369		1	0.3464	0.3688		1	0.3446	0.3493
	2	0.3371	0.3493		2	0.3551	0.3760		2	0.3458	0.3623
ша	3	0.3412	0.3525	ши	3	0.3533	0.3624	Ue	3	0.3500	0.3657
H2	4	0.3407	0.3462	H4	4	0.3493	0.3591	H6	4	0.3485	0.3524
	5	0.3446	0.3493		5	0.3500	0.3657				
	6	0.3441	0.3428		6	0.3458	0.3623				

Tolerance on each Hue bin (x,y) is \pm -- 0.01.

				40	000K	(I _F = 120	mA)				
Rank	-	х	у	Rank	-	x	у	Rank	-	х	у
	1	0.3703	0.3726		1	0.3784	0.3647		1	0.3746	0.3689
	2	0.3736	0.3874		2	0.3806	0.3725		2	0.3784	0.3841
C4	3	0.3871	0.3959	G3	3	0.3865	0.3762	G5	3	0.3849	0.3882
G1	4	0.3849	0.3881		4	0.3890	0.3842		4	0.3806	0.3726
	5	0.3784	0.3841		5	0.3952	0.3880				
	6	0.3766	0.3765		6	0.3898	0.3716				
	1	0.3670	0.3578		1	0.3871	0.3959		1	0.3806	0.3726
	2	0.3703	0.3726		2	0.4006	0.4044		2	0.3849	0.3882
00	3	0.3766	0.3765	C4	3	0.3952	0.3880	00	3	0.3914	0.3922
G2	4	0.3746	0.3689	G4	4	0.3890	0.3842	G6	4	0.3865	0.3762
	5	0.3806	0.3725		5	0.3914	0.3922				
	6	0.3784	0.3647		6	0.3849	0.3881				



				38	500K	(<i>I</i> _F = 120	mA)				
Rank	-	х	у	Rank	-	x	у	Rank	-	х	у
	1	0.3943	0.3853		1	0.4018	0.3752		1	0.3983	0.3804
	2	0.3996	0.4015		2	0.4050	0.3837		2	0.4042	0.3970
F1	3	0.4148	0.4090	F3	3	0.4118	0.3869	F5	3	0.4115	0.4006
F1	4	0.4115	0.4006		4	0.4153	0.3955		4	0.4050	0.3837
	5	0.4042	0.3970		5	0.4223	0.3990				
	6	0.4013	0.3887		6	0.4147	0.3814				
	1	0.3889	0.3690		1	0.4148	0.4090		1	0.4050	0.3837
	2	0.3943	0.3853		2	0.4299	0.4165		2	0.4115	0.4006
F2	3	0.4013	0.3887	F4	3	0.4223	0.3990	F6	3	0.4188	0.4041
ΓZ	4	0.3983	0.3804	F4	4	0.4153	0.3955	го	4	0.4118	0.3869
	5	0.4050	0.3837		5	0.4188	0.4041				
	6	0.4018	0.3752		6	0.4115	0.4006				

Tolerance on each Hue bin (x,y) is \pm -0.01.

				30	000K	(<i>I</i> _F = 120	mA)				
Rank	-	х	у	Rank	-	х	у	Rank	-	х	у
	1	0.4223	0.3990		1	0.4260	0.3854		1	0.4244	0.3923
	2	0.4299	0.4165	E 3	2	0.4303	0.3943		2	0.4324	0.4100
E1	3	0.4431	0.4213		3	0.4361	0.3964	E5	3	0.4388	0.4123
E1	4	0.4388	0.4123		4	0.4406	0.4055		4	0.4303	0.3944
	5	0.4324	0.4100		5	0.4468	0.4077				
	6	0.4284	0.4011		6	0.4373	0.3893				
	1	0.4147	0.3814		1	0.4431	0.4213		1	0.4303	0.3944
	2	0.4223	0.3990		2	0.4562	0.4260		2	0.4388	0.4123
E2	3	0.4284	0.4011	EA	3	0.4468	0.4077	Ee	3	0.4452	0.4146
EZ	4	0.4244	0.3923	E4	4	0.4406	0.4055	E6	4	0.4361	0.3964
	5	0.4303	0.3943		5	0.4451	0.4146				
	6	0.4260	0.3854		6	0.4388	0.4123				



				27	700K	(<i>I</i> _F = 120	mA)				
Rank	-	х	у	Rank	-	х	у	Rank	-	х	у
	1	0.4468	0.4077		1	0.4483	0.3919		1	0.4477	0.3998
	2	0.4562	0.4260		2	0.4534	0.4011		2	0.4576	0.4183
D4	3	0.4688	0.4290	D3	3	0.4591	0.4025	DE	3	0.4637	0.4197
D1	4	0.4636	0.4197		4	0.4644	0.4118	D5	4	0.4534	0.4012
	5	0.4576	0.4183		5	0.4703	0.4132				
	6	0.4527	0.4090		6	0.4593	0.3944				
	1	0.4373	0.3893		1	0.4688	0.4290		1	0.4534	0.4012
	2	0.4468	0.4077		2	0.4813	0.4319		2	0.4637	0.4197
Da	3	0.4527	0.4090	D4	3	0.4703	0.4132	De	3	0.4697	0.4211
D2	4	0.4477	0.3998	D4	4	0.4644	0.4118	D6	4	0.4591	0.4025
	5	0.4534	0.4011		5	0.4697	0.4211				
	6	0.4483	0.3919		6	0.4636	0.4197				



5.3 Flux Bin

2700K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
Ф Din	Lumen (lm) a	Lumen (lm) at $I_F = 120 \text{ mA}$		
$\Psi_{\scriptscriptstyle V}$ DIII	$\Phi_{\scriptscriptstyle V}$ Bin Min M			
CF	33.5	38		
FI	38.0	42.5		
IL	42.5 47.0			
LO	47.0 51.5			

3000K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
Ф Din	Lumen (lm) at $I_F = 120 \text{ mA}$			
$\Phi_{ m v}$ Bin	Min Max			
DG	35.0	39.5		
GJ	39.5	44.0		
JM	44.0	48.5		
MP	48.5 53.0			

3500K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
љ Din	Lumen (lm) at I _F = 120 mA Min Max			
$\Phi_{ m v}$ Bin				
EH	36.5	41.0		
HK	41.0	45.5		
KN	45.5 50.0			
NQ	50.0 54.5			

4000K	$\Phi_{ m v}$ Luminous Flux Spec. Table		
љ D:	Lumen (lm) at $I_F = 120 \text{ mA}$		
$\Phi_{ m v}$ Bin	Min	Max	
EH	36.5 41.0		
HK	41.0 45.5		
KN	45.5 50.0		
NQ	50.0 54.5		

5000K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
љ Din	Lumen (lm) at $I_F = 120 \text{ mA}$			
$\Phi_{ m v}$ Bin	Min	Max		
EH	36.5	41.0		
HK	41.0	45.5		
KN	45.5	50.0		
NQ	50.0 54.5			

5700K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
Φ. Din	Lumen (lm) at I _F = 120 mA Min Max			
$\Phi_{ m v}$ Bin				
EH	36.5	41.0		
HK	41.0	45.5		
KN	45.5	50.0		
NQ	50.0 54.5			

6500K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
љ Din	Lumen (lm) at $I_F = 120 \text{ m/s}$			
$\Phi_{ m v}$ Bin	Min	Max		
EH	36.5	41.0		
HK	41.0	45.5		
KN	45.5	50.0		
NQ	50.0 54.5			

Tolerance on each Luminous Flux bin is +/- 10%.



5.4 Voltage Bin

V _F Spec. Table					
V Die	Forward Voltage (volts) at <i>I</i> _F = 120mA				
V _F Bin	Min Max				
VA	2.8	2.9			
V0	2.9	3.0			
V1	3.0	3.1			
V2	3.1	3.2			
V3	3.2	3.3			

Tolerance on each Forward Voltage bin is +/- 0.1V

6. Bin Code List

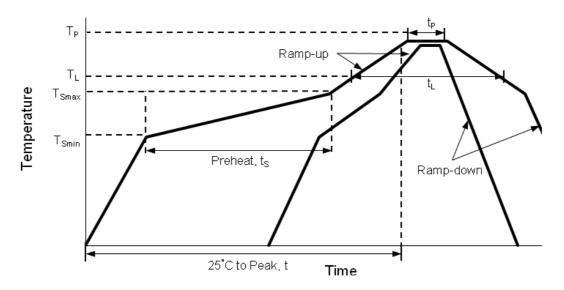
% Notes: Full Rank on Label

Example: V1/HK/G5

Forward Voltage Rank	Luminous Flux Rank	Color Rank
V1	HK	G5



7. Reflow Soldering Characteristics



Profile Feature	Lead Free Assembly
Average Ramp-Up Rate (T _{Smax} to T _P)	3°C / second max
Preheat Temperature Min (T _{Smin})	150°C
Preheat Temperature Max (T _{Smax})	200°C
Preheat Time (t _{Smin} to t _{Smax})	60 – 180 seconds
Time Maintained Above Temperature (T _L)	217°C
Time Maintained Above Time (t _L)	60 – 150 seconds
Peak / Classification Temperature (T _P)	260°C
Time Within 5°C of Actual Peak Temperature (t _P)	5 seconds
Ramp – Down Rate	6°C / second max
Time 25°C to Peak Temperature	8 minutes max

Notes:

- The LEDs can be soldered using the reflow soldering or hand soldering method. The recommended hand soldering condition is 350 °C max. and 2 secs max. for one time only, and the recommended reflow soldering condition is 260 °C max. and 5 secs max. for three times max.
- 2. All temperatures refer to topside of the package, measured on the package body surface.



- 3. The soldering condition referring to J-STD-020. The storage ambient for the LEDs should not exceed 30 °C temperature or 70% relative humidity. It is recommended that LEDs out of their original packaging are soldered within one week. For extended storage out of their original packaging, it is recommended that the LEDs were stored in a sealed container with appropriate desiccant, or desiccators with nitrogen ambient. If the LEDs were unpacked more than 168hrs, baking the LEDs at 60 °C for 24 hrs before soldering process.
- 4. The soldering profile could be further referred to different soldering grease material characteristic. The grease vendor will provide this information.
- 5. A rapid-rate process is not recommended for the LEDs cooling down from the peak temperature.
- 6. Although the recommended reflow conditions are specified above, the reflow or hand soldering condition at the lowest possible temperature is desirable for the LEDs.
- 7. LiteOn cannot make a guarantee on the LEDs which have been already assembled using the dip soldering method.



8. Reliability Test

No	Test item	Test Condition	Duration	Number of Damaged
1	Steady State Operating Life of High Temperature (HTOL)	Ts=55℃, <i>I</i> _F =120mA	1000 hrs	0/20
2	Steady State Operating Life of High Temperature (HTOL)	Ts=85°ℂ , <i>I</i> _F =120mA	1000 hrs	0/20
3	Steady State Operating Life of Low Temperature (LTOL)	Ta=-40°C , <i>I</i> _F =120mA	1000 hrs	0/20
4	Pulse Wet Operating Life of High Temperature (PWHTOL)	60°C/90%RH, <i>I</i> _F =120mA 30mins ON/30min OFF	500 hrs	0/20
5	High Temperature Storage (HTS)	100℃	1000 hrs	0/20
6	Low Temperature Storage (LTS)	-40°C	1000 hrs	0/20
7	Thermal Cycle (TC)	-40°C~100°C 30min dwell 5min transfer	200 cycle	0/20
8	Thermal Shock (TS)	-40°C ~100°C 20min dwell 20sec transfer	200 cycle	0/20
9	Solder Resistance (SR)	265°C, 3X MSL	5sec	0/20
10	Solder Ability (SA)	245°ℂ5sec, 95% coverage	5sec	0/11
11	Salt Spread (SS)	35℃, 30g/m²/day	48hrs	0/11

Criteria for Judging the Damage

Item	Symbol	Test Condition Criteria for		r Judgment	
item	Symbol	rest Condition	Min.	Max.	
Forward Voltage	V_{F}	<i>I</i> _F =Typical Current		U.S.L. x 1.1	
Luminous Flux	lm	<i>I</i> _F =Typical Current	L.S.L. x 0.7		
CCX&CCY	x,y	<i>I</i> _F =Typical Current		Shift<0.02	



9. User Guide

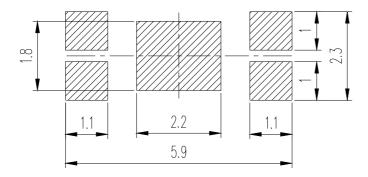
Cleaning

Do not use unspecified chemical liquid to clean LED they could harm the package. If cleaning is necessary, immerse the LED in ethyl alcohol or isopropyl alcohol at normal temperature for less than one minute.

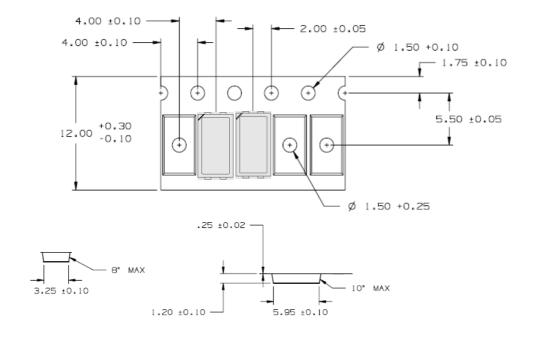
Recommend Printed Circuit Board Attachment Pad

Infrared / vapor phase

Reflow Soldering



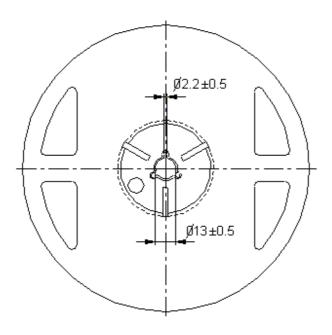
Package Dimensions of Tape



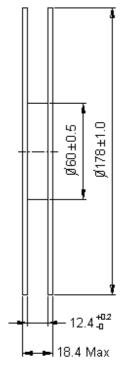
Note: All dimensions are in millimeters (inches).



■ Package Dimensions of Reel



Note: 01. The tolerance unless mentioned is±0.1mm 02. The measured unit is "mm"



Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 7 inch reel-3000 pieces per reel.
- 3. Minimum packing quantity is 500 pieces for remainders.
- 4. The maximum number of consecutive missing lamps is two.
- 5. In accordance with EIA-481-1-B specifications.



10. Cautions

10.1 Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

10.2 Storage

This product is qualified as Moisture sensitive Level 3 per JEDEC J-STD-020 Precaution when handing this moisture sensitive product is important to ensure the reliability of the product.

The package is sealed:

The LEDs should be stored at 30°C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

The package is opened:

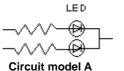
The LEDs should be stored at 30°C or less and 60%RH or less. Moreover, the LEDs are limited to solder process within 168hrs. If exceeding the storage limiting time since opened, that we recommended to baking LEDs at 60°C at least 24hrs. To seal the remainder LEDs return to package, it's recommended to be with workable desiccants in original package.

10.3 Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

10.4 Drive Mode

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below



uit model A Circuit model B

(A) Recommended circuit.

LED



(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

10.5 ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED. Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- All devices, equipment, and machinery must be properly grounded.
- Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents. To verify for ESD damage, check for "light up" and V_F of the suspect LEDs at low currents. The V_F of "good" LEDs should be >2.0V@0.1mA for InGaN product and >1.4V@0.1mA for AllnGaP product.

10.6 Suggested Checking List:

- Training and Certification
 - 1. Everyone working in a static-safe area is ESD-certified?
 - 2. Training records kept and re-certification dates monitored?
- Static-Safe Workstation & Work Areas
 - 1. Static-safe workstation or work-areas have ESD signs?
 - 2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
 - 3. All ionizer activated, positioned towards the units?
 - 4. Each work surface mats grounding is good?
- Personnel Grounding
 - Every person (including visitors) handling ESD sensitive (ESDS) items wear wrist strap, heel strap or conductive shoes with conductive flooring?
 - 2. If conductive footwear used, conductive flooring also present where operator stand or walk?
 - 3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V*?



- 4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DLs?
- All wrist strap or heel strap checkers calibration up to date?
 Note: *50V for Blue LED.

Device Handling

- 1. Every ESDS items identified by EIA-471 labels on item or packaging?
- 2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
- 3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
- 4. All flexible conductive and dissipative package materials inspected before reuse or recycle?

Others

- 1. Audit result reported to entity ESD control coordinator?
- 2. Corrective action from previous audits completed?
- 3. Are audit records complete and on file?

10.7 Others:

- Do not put any pressure on the light emitting surface either by finger or any hand tool and do not stack the products. Stress or pressure may cause damage to the wires of the LED array.
- This product is not designed for the use under any of the following conditions, please confirm the performance and reliability are well enough if you use it under any of the following conditions
- Do not use sulfur-containing materials in commercial products including the materials such as seals and adhesives that may contain sulfur.
- Do not put this product in a place with a lot of moisture (over 85% relative humidity), dew condensation, briny air, and corrosive gas (Cl, H₂S, NH₃, SO₂, NO_X, etc.), exposure to a corrosive environment may affect silver plating.
- The appearance and specifications of the product may be modified for improvement without prior notice.



Revision History:

Revision Date:

Version	Page	Content of Change	Date Record
2.0	18	Add flux high bin	2015.05.19
2.1	5	Modify flux spec	2015.05.21
2.2	2	New lead frame	2016.07.25
2.3	P4,5,6,8,19,22	Add Vf bin 2.8-2.9V and I-V curve, update new Reliability	2016.10.12